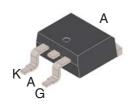
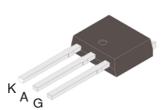


TO-252AA (DPAK)



TO-251AA (IPAK)





On-State Current

Gate Trigger Current

12 Amp

 $< 200 \, \mu A$

Off-State Voltage

800 V

FEATURES

- Glass/passivated die junctions
- Medium current SCR
- Low thermal resistance
- High surge current capability
- Low forward voltage drop
- Solder dip 260°C, 10s
- Component in accordance to RoHS 2011/65/EU and WEEE 2002/96/EC
- Meets MSL level 3, per J-STD-020, LF maximum peak of 260° C

MECHANICAL DATA

- Case: TO-252AA (DPAK) & TO-251AA (IPAK). Epoxy meets UL 94V-0 flammability rating.
- Polarity: As marked on the body.
- **Terminals:** Matte tin plated leads, solderable per MIL-STD-750 Method 2026, J-STD-002 and JESD22-B102. Consumer grade, meets JESD 201 class 1A whisker test.

TYPICAL APPLICATIONS

Thanks to highly sensitive triggering levels, the FS12xxxD SCR series is suitable for all applications where available gate current is limited, such as ground fault circuit interruptors, pilot circuits in solid state relays, stand-by mode power supplies, smoke and alarm detectors.

Maximun Ratings and Electrical Characteristics at 25°C

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
I _{T(RMS)}	On-state Current	180° Conduction Angle	12	А
I _{T(AV)}	Average On-state Current	Half Cycle, Θ = 180 °, T _C = 95 °C	7.6	А
I _{TSM}	Non-repetitive On-State Current	Half Cycle, 60 Hz	100	А
I _{TSM}	Non-repetitive On-State Current	Half Cycle, 50 Hz	91	А
I ² t	Fusing Current	t _p = 10ms, Half Cycle	41	A ² s
I _{GM}	Peak Gate Current	20 µs max.	2	А
P _{GM}	Peak Gate Dissipation	20 µs max.	5	W
$P_{G(AV)}$	Gate Dissipation	20 ms max.	0.5	W
T _j	Operating Temperature		(-40 to + 125)	°C
T _{stg}	Storage Temperature		(-40 to + 150)	°C
T _{sld}	Soldering Temperature	10s max.	260	°C

SYMBOL	SYMBOL PARAMETER CONDITION		VOLTAGE	Unit
OTTVIDOL TATIFACTOR		OONDITIONS	N	
V_{DRM}/V_{RRM}	Repetitive Peak Off State Voltage	$R_{GK} = 1 \text{ k}\Omega$	800	V



Electrical Characteristics at Tamb = 25 °C

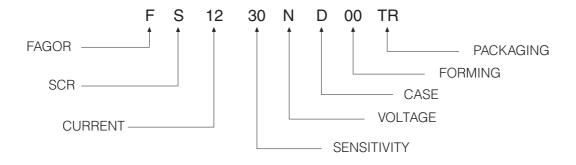
SYMBOL	PARAMETER	CONDITIONS			SENSITIVITY	Unit
01202					30	
I _{GT}	Gate Trigger Current	$V_{\rm D} = 12 V_{\rm DC}, \ R_{\rm L} = 100 \Omega$	2	MIN	-	
				MAX	200	μΑ
V _{GT}	Gate Trigger Voltage	$V_D = 12 V_{DC}, R_L = 100 \Omega$	2	MAX	1.5	V
V_{GD}	Gate Non Trigger Voltage	$V_D = V_{DRM}, R_L = 3.3 \; k\Omega, $	R_{GK} = 220 Ω	MIN	0.1	V
		T _j = 125 °C				
V _{RGM}	Reverse Gate Voltage	, I _{RG} = 10 μA,		MIN	8	V
I _H	Holding Current	I _G = 0.1 A, V _D = 12 V		MAX	6	mA
IL	Latching Current	$I_G = 0.1 \text{ A}, V_D = 12 \text{ V}$		MAX	10	mA
dV / dt	Critical Rate of Voltage Rise	$V_{D} = 0.67 \times V_{DRM}, R_{GK} = 1 \text{ k}\Omega, $		MIN	5	V/µs
		T _j = 125 °C				
dI / dt	Critical Rate of Current Rise	$I_G = 2 \times I_{GT}$ tr $\leq 100 \text{ ns},$	f = 60 Hz,	MIN	50	A/µs
		T _j = 125 °C	:			
V _{TM}	On-state Voltage	at $I_T = 20$ Amp, $tp = 380 \mu$	S	MAX	1.9	V
I _{DRM} / I _{RRM}	Off-State Leakage Current	$V_D = V_{DRM}, R_{GK} = 1 \text{ k}\Omega$	T _j = 125 °C	MAX	0.5	mA
		$V_R = V_{RRM}$,	T _j = 25 °C	MAX	10	μΑ

Thermal resistance

SYMBOL	PARAMETER	CONDITIONS		Value	Unit
R _{th(j-c)}	Thermal Resistance Junction-Case for DC			2.2	°C/W
R _{th(j-a)}	Thermal Resistance	S = 0.5cm ²	DPAK	70	°C/W
Junction-An	Junction-Amb for DC		IPAK	100	O/VV

S = Copper surface under tab

Part Number Information

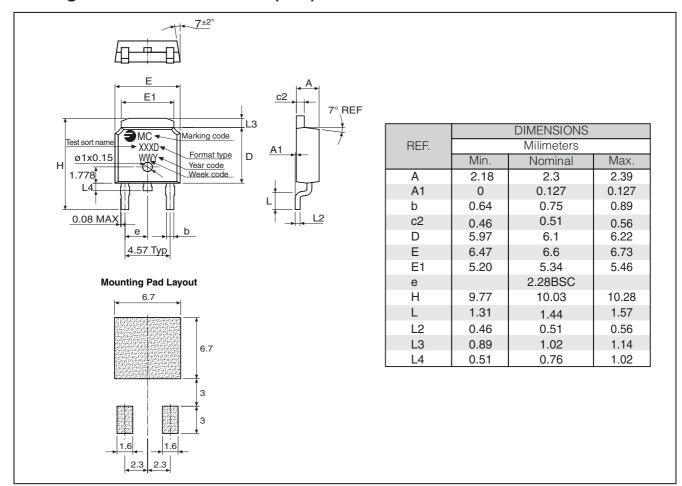




Ordering information

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	BASE QUANTITY	UNIT WEIGHT (g)
FS1230ND 00TR	TR	13" diameter tape and reel	2,500	0.30

Package Outline Dimensions: (mm) TO-252AA (DPAK)

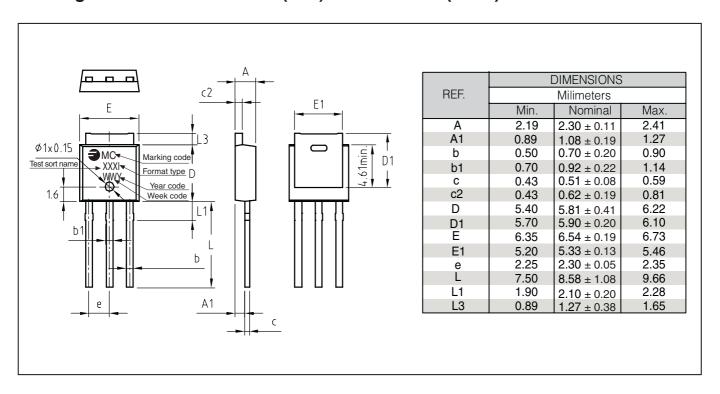




Ordering information

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	BASE QUANTITY	UNIT WEIGHT (g)
FS1230NI 00TU	TU	TUBE	4,000	0.40

Package Outline Dimensions: (mm) TO-251AA (IPAK)





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 1: Maximum on-state dissipation versus average on-state current.

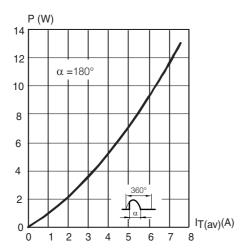


Fig. 3: Maximum permissible rms current versus mounting base temperature.

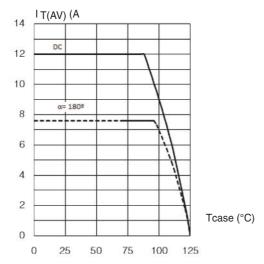


Fig. 5: Maximum permissible repetitive rms onstate current versus surge duration for sinusoidal currents, f = 50 Hz.

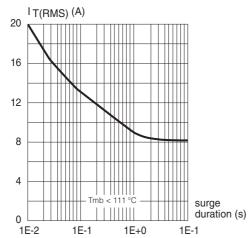


Fig. 2: Maximum permissible nonrepetitive peak on-state current versus pulse widht for sinusoidal currents.

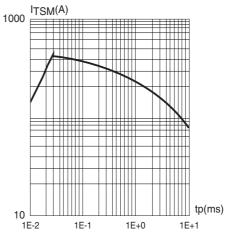


Fig. 4: Maximum permissible non repetitive peak on-state current versus number of cycles for sinusoidal currents.

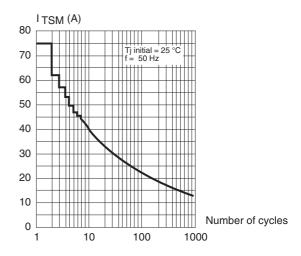


Fig. 6: Normalised gate trigger voltage versus junction temperature.

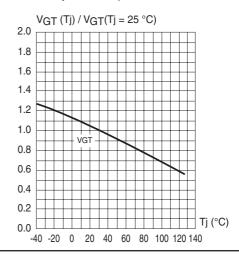




Fig. 7: Normalised gate trigger current versus junction temperature.

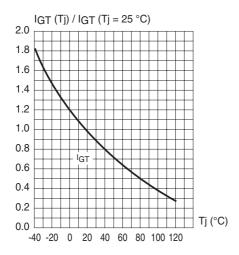


Fig. 9: Normalised holding current versus junction temperature.

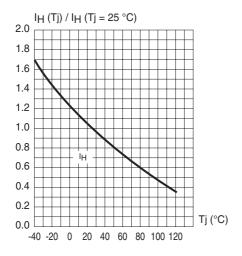


Fig. 8: Normalised latching current versus junction temperature.

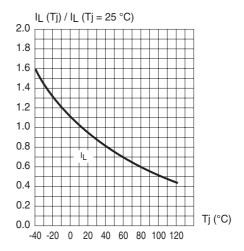


Fig. 10: Maximum on-state characteristic.

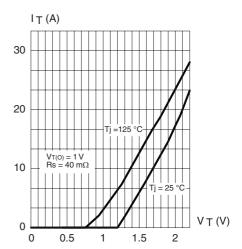
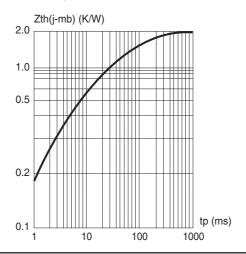


Fig. 11: Transient thermal impedance versus pulse width.





Revision History

Date	Revision	Description of Changes	
May-2013	0	Original Data Sheet	
Mar-2015 1		Unify FS1230ND and FS1230NI in a single Data Sheet	

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